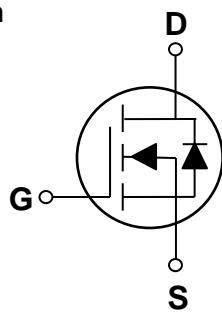


General Description

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

TO220 Pin Configuration



BVDSS	RDS(ON)	ID
65V	3.3mΩ	150A

Features

- 65V, 150A, RDS(ON) = 3.3mΩ@VGS = 10V
- Improved dv/dt capability
- Fast switching
- 100% EAS Guaranteed
- Green Device Available

Applications

- Networking
- Load Switch
- LED applications
- Quick Charger



Absolute Maximum Ratings $T_c=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Rating	Units
V _{Ds}	Drain-Source Voltage	65	V
V _{Gs}	Gate-Source Voltage	+20/-12	V
I _D	Drain Current – Continuous ($T_c=25^\circ\text{C}$)	150	A
	Drain Current – Continuous ($T_c=100^\circ\text{C}$)	94	A
I _{DM}	Drain Current – Pulsed ¹	600	A
EAS	Single Pulse Avalanche Energy ²	245	mJ
I _{AS}	Single Pulse Avalanche Current ²	70	A
P _D	Power Dissipation ($T_c=25^\circ\text{C}$)	183	W
	Power Dissipation – Derate above 25°C	1.47	W/°C
T _{STG}	Storage Temperature Range	-50 to 150	°C
T _J	Operating Junction Temperature Range	-50 to 150	°C

Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
R _{θJA}	Thermal Resistance Junction to ambient	---	62	°C/W
R _{θJC}	Thermal Resistance Junction to Case	---	0.68	°C/W

Electrical Characteristics ($T_J=25\text{ }^{\circ}\text{C}$, unless otherwise noted)
Off Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$, $I_D=250\mu\text{A}$	65	---	---	V
$\Delta BV_{DSS}/\Delta T_J$	BV_{DSS} Temperature Coefficient	Reference to $25\text{ }^{\circ}\text{C}$, $I_D=1\text{mA}$	---	0.05	---	$\text{V}/\text{ }^{\circ}\text{C}$
I_{DSS}	Drain-Source Leakage Current	$V_{DS}=60\text{V}$, $V_{GS}=0\text{V}$, $T_J=25\text{ }^{\circ}\text{C}$	---	---	1	μA
		$V_{DS}=48\text{V}$, $V_{GS}=0\text{V}$, $T_J=85\text{ }^{\circ}\text{C}$	---	---	10	μA
I_{GSS}	Gate-Source Leakage Current	$V_{GS}=20\text{V}$, $V_{DS}=0\text{V}$	---	---	100	nA

On Characteristics

$R_{DS(\text{ON})}$	Static Drain-Source On-Resistance	$V_{GS}=10\text{V}$, $I_D=20\text{A}$	---	2.7	3.3	$\text{m}\Omega$
		$V_{GS}=4.5\text{V}$, $I_D=10\text{A}$	---	4	5.3	$\text{m}\Omega$
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{GS}=V_{DS}$, $I_D = 250\mu\text{A}$	1	1.6	2.5	V
			---	-5	---	$\text{mV}/\text{ }^{\circ}\text{C}$
g_{fs}	Forward Transconductance	$V_{DS}=10\text{V}$, $I_D=5\text{A}$	---	11	---	S

Dynamic and switching Characteristics

Q_g	Total Gate Charge ^{3, 4}	$V_{DS}=48\text{V}$, $V_{GS}=10\text{V}$, $I_D=10\text{A}$	---	59	120	nC
Q_{gs}	Gate-Source Charge ^{3, 4}		---	10.4	20	
Q_{gd}	Gate-Drain Charge ^{3, 4}		---	19.6	38	
$T_{d(on)}$	Turn-On Delay Time ^{3, 4}	$V_{DD}=30\text{V}$, $V_{GS}=10\text{V}$, $R_G=6\Omega$ $I_D=1\text{A}$	---	22	44	ns
T_r	Rise Time ^{3, 4}		---	14	28	
$T_{d(off)}$	Turn-Off Delay Time ^{3, 4}		---	40	80	
T_f	Fall Time ^{3, 4}		---	20	40	
C_{iss}	Input Capacitance	$V_{DS}=25\text{V}$, $V_{GS}=0\text{V}$, $F=1\text{MHz}$	---	3620	7200	pF
C_{oss}	Output Capacitance		---	2395	4800	
C_{rss}	Reverse Transfer Capacitance		---	177	350	
R_g	Gate resistance	$V_{GS}=0\text{V}$, $V_{DS}=0\text{V}$, $F=1\text{MHz}$	---	1.8	3.6	Ω

Drain-Source Diode Characteristics and Maximum Ratings

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_s	Continuous Source Current	$V_G=V_D=0\text{V}$, Force Current	---	---	150	A
I_{SM}	Pulsed Source Current		---	---	300	A
V_{SD}	Diode Forward Voltage	$V_{GS}=0\text{V}$, $I_s=1\text{A}$, $T_J=25\text{ }^{\circ}\text{C}$	---	---	1	V

Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. $V_{DD}=25\text{V}$, $V_{GS}=10\text{V}$, $L=0.1\text{mH}$, $I_{AS}=70\text{A}$, $R_G=25\Omega$, Starting $T_J=25\text{ }^{\circ}\text{C}$.
3. The data tested by pulsed , pulse width $\leq 300\text{us}$, duty cycle $\leq 2\%$.
4. Essentially independent of operating temperature.



STEIF POWER
TECHNOLOGY

65V N-Channel MOSFETs

SPP6974-5

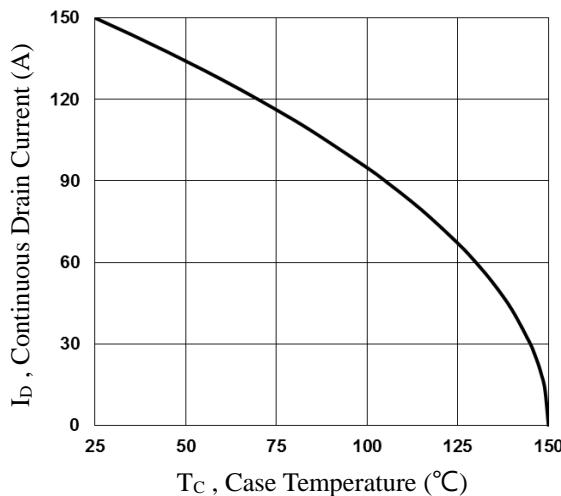


Fig.1 Continuous Drain Current vs. T_C

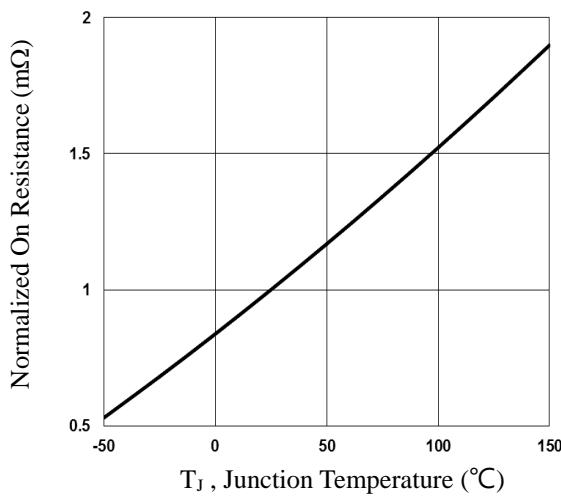


Fig.2 Normalized $R_{DS(ON)}$ vs. T_J

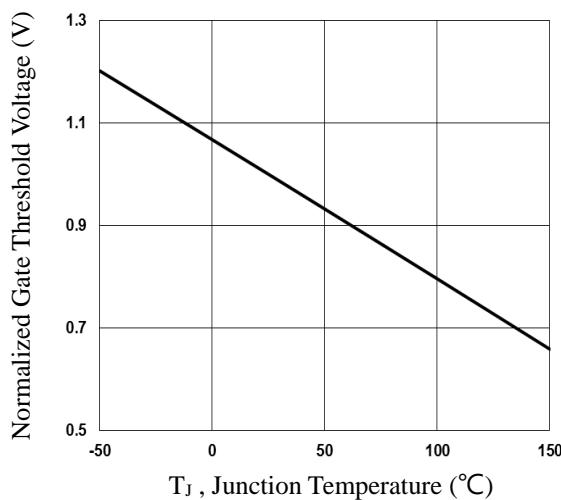


Fig.3 Normalized V_{th} vs. T_J

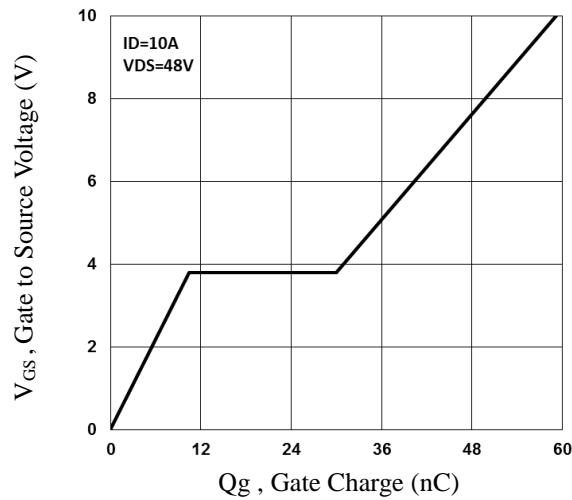


Fig.4 Gate Charge Characteristics

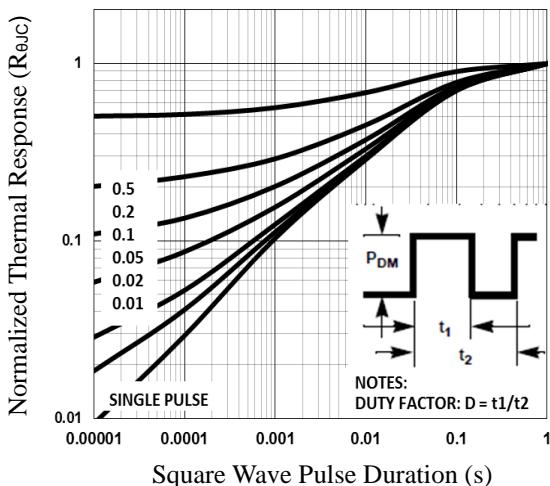


Fig.5 Normalized Transient Impedance

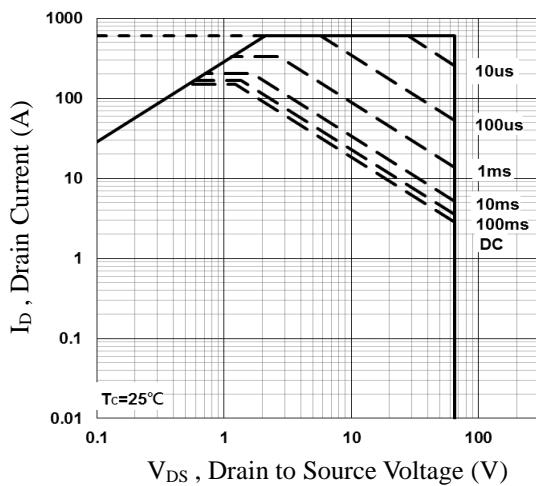


Fig.6 Maximum Safe Operation Area

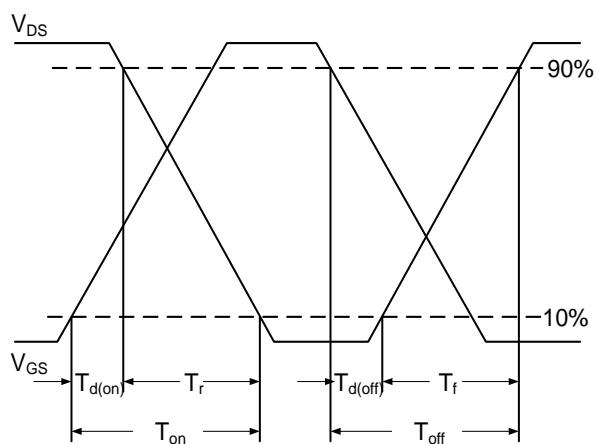


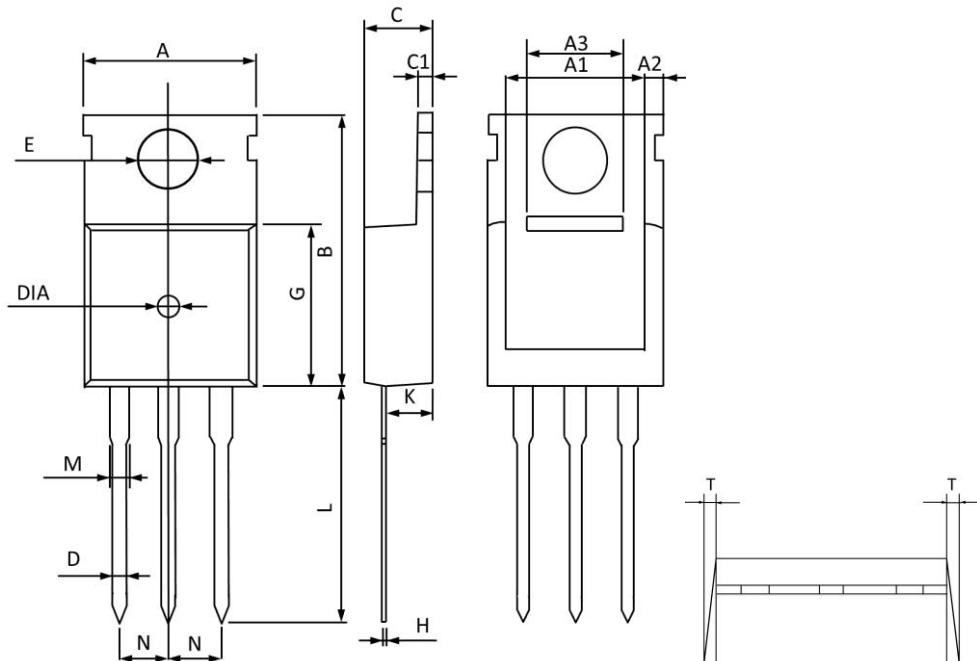
Fig.7 Switching Time Waveform



Fig.8 Gate Charge Waveform



TO220 PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MAX	MIN	MAX	MIN
A	10.300	9.700	0.406	0.382
A1	8.840	8.440	0.348	0.332
A2	1.250	1.050	0.049	0.041
A3	5.300	5.100	0.209	0.201
B	16.200	15.400	0.638	0.606
C	4.680	4.280	0.184	0.169
C1	1.500	1.100	0.059	0.043
D	1.000	0.600	0.039	0.024
E	3.800	3.400	0.150	0.134
G	9.300	8.700	0.366	0.343
H	0.600	0.400	0.024	0.016
K	2.700	2.100	0.106	0.083
L	13.600	12.800	0.535	0.504
M	1.500	1.100	0.059	0.043
N	2.590	2.490	0.102	0.098
T	W0.35		W0.014	
DIA	Φ1.5 TYP.	deep0.2 TYP.	Φ0.059 TYP.	deep0.008 TYP.